

Lead-Tin-Copper

SLOTOLET CSP 10-1

SLOTOLET CSP 10-1 is a high acidic, fluoride-free electrolyte for the deposition of alloy coatings based on the ternary system lead-tin-copper.

The ternary alloy of 88 % lead, 10 % tin and 2 % copper is used for the production of bearing half liners. The deposition even at thick coatings is smooth and free of dendrites.

The information in this data sheet is based on laboratory as well as practical experience. Figures quoted for operating limits and replenishment quantities are for guidance. Actual values necessary will depend on the components being plated (material and geometry), their application and plating plant conditions.

Important:

Please read these instructions carefully and follow recommendations given.

We reserve the right to make technical changes as necessary.

In the interests of safety, please pay attention to the R- and S- phrases on the drum label.

The shelf life of the additives is generally 18 months.

The date of production is taken from the first 3 figures of the batch number.

Figure 1 = year; figures 2-3 = month; figures 4-7 = batch number; (UK labels use a 4 digit year code).

For the storage of chemical products only the TRGS 514 and TRGS 515 Regulations must be followed. The Hazardous Goods Regulation (ADR/GGVS) are only valid for transportation and must not be applied to storage.

